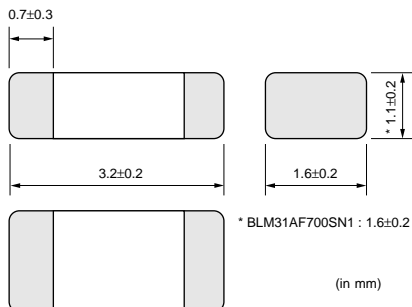


Chip EMIFIL® Inductor Type Chip Ferrite Beads

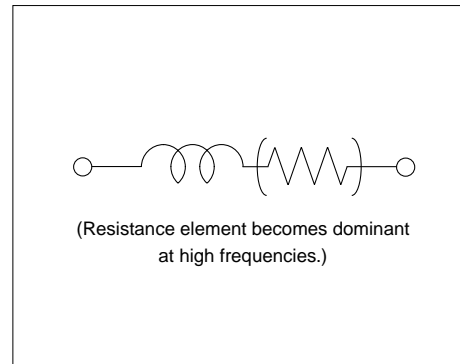
BLM31A Series (1206 Size)

● For your new designs, alternative parts should be used. These parts should be used only for existing design. Please consult with us for details.

Dimension



Equivalent Circuit



Packaging

Code	Packaging	Minimum Quantity
L	180mm Embossed Tape	3000
K	330mm Embossed Tape	10000
B	Bulk(Bag)	1000

• Only applied to **BLM31AF700SN1**

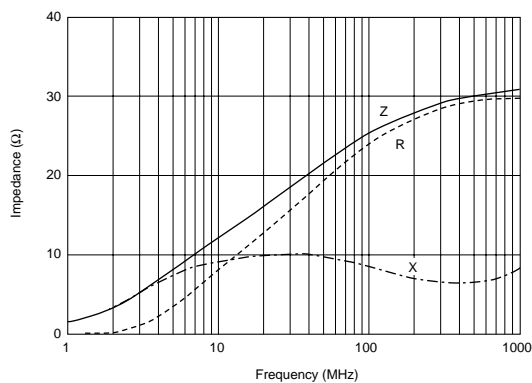
Code	Packaging	Minimum Quantity
L	180mm Embossed Tape	2500
K	330mm Embossed Tape	8000
B	Bulk(Bag)	1000

Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance(max.)	Operating Temperature Range	Number of Circuits
BLM31AJ260SN1 □	26ohm±25%	-	500mA	0.05ohm	-55°C to +125°C	1
BLM31AF700SN1 □	70ohm±25%	-	200mA	0.15ohm	-55°C to +125°C	1
BLM31AJ601SN1 □	600ohm±25%	-	200mA	0.90ohm	-55°C to +125°C	1

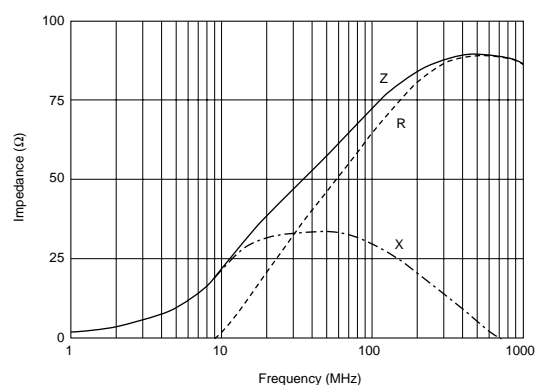
Impedance-Frequency Characteristics

BLM31AJ260SN1



Impedance-Frequency Characteristics

BLM31AF700SN1



Continued on the following page.

● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

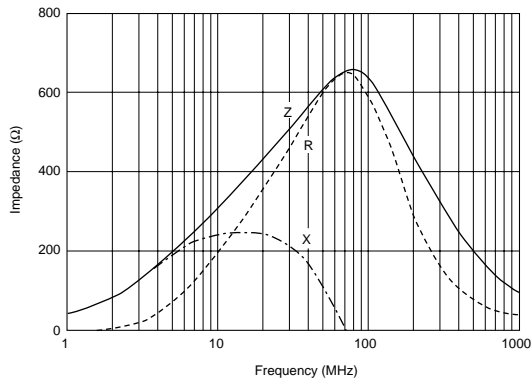
Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., Ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

Continued from the preceding page.

■ Impedance-Frequency Characteristics

BLM31AJ601SN1



■ ⚠ Caution/Notice

⚠ Caution (Rating)

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

⚠ Note:

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